

PATENT ASSIGNMENT

Electronic Version v1.1

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SUBMISSION TYPE:	NEW ASSIGNMENT										
NATURE OF CONVEYANCE:	ASSIGNMENT										
CONVEYING PARTY DATA											
<table border="1"><thead><tr><th>Name</th><th>Execution Date</th></tr></thead><tbody><tr><td>Feng-Lung Lin</td><td>09/11/2010</td></tr><tr><td>Kuan-Liang Wu</td><td>09/11/2010</td></tr><tr><td>Che-Rong Liang</td><td>09/11/2010</td></tr><tr><td>Fei-Gwo Tsai</td><td>09/11/2010</td></tr></tbody></table>	Name	Execution Date	Feng-Lung Lin	09/11/2010	Kuan-Liang Wu	09/11/2010	Che-Rong Liang	09/11/2010	Fei-Gwo Tsai	09/11/2010	
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Kuan-Liang Wu	09/11/2010										
Che-Rong Liang	09/11/2010										
Fei-Gwo Tsai	09/11/2010										
RECEIVING PARTY DATA											
Name:	Taiwan Semiconductor Manufacturing Company, Ltd.										
Street Address:	No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park										
City:	Hsin-Chu										
State/Country:	TAIWAN										
Postal Code:	300-77										
PROPERTY NUMBERS Total: 1											
<table border="1"><thead><tr><th>Property Type</th><th>Number</th></tr></thead><tbody><tr><td>Application Number:</td><td>13188347</td></tr></tbody></table>	Property Type	Number	Application Number:	13188347							
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Application Number:	13188347										
CORRESPONDENCE DATA											
Fax Number: (214)200-0853 <i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>											
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ATTORNEY DOCKET NUMBER:	24061.1906										
NAME OF SUBMITTER:	Thomas W. Kelton										
Total Attachments: 4 source=1906Assignment#page1.tif source=1906Assignment#page2.tif source=1906Assignment#page3.tif source=1906Assignment#page4.tif											

OP \$40.00 13188347

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PATENT
REEL: 026641 FRAME: 0959

ASSIGNMENT

WHEREAS, we,

- | | | | |
|-----|----------------|----|---|
| (1) | Feng-Lung Lin | of | No. 13, Lane 48, Zhuyuan Road, Baoshan Shiang
Hsinchu County 308, Taiwan, R.O.C. |
| (2) | Kuan-Liang Wu | of | 7F, No. 23, Lane 294, Guangfu S. Road, Dan-an District
Taipei City 106, Taiwan, R.O.C. |
| (3) | Che-Rong Laing | of | 5F, No. 7, Land 120, Hulin Street, Sinyi District
Taipei City 110, Taiwan, R.O.C. |
| (4) | Fei-Gwo Tsai | of | 20F-5, No. 19, Lane 370, Gongyuan S. Road
Tainan City 704, Taiwan, R.O.C. |

have invented certain improvements in

HYBRID MULTI-LAYER MASK

for which we have executed an application for Letters Patent of the United States of America,

_____ of even date filed herewith; and
 X filed on October 13, 2008 and assigned application no. 12/250,338 and;

WHEREAS, we authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu, Taiwan 300-77, Republic of China, is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for One Dollar (\$1.00) and other good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

Docket No.: 2008-0326 / 24061.1095
Customer No.: 42717

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name: Feng-Lung Lin

Residence Address: No. 13, Lane 48, Zhuyuan Road, Baoshan Shiang
Hsinchu County 308, Taiwan, R.O.C.

Dated: ✓ 9/11/2008

✓ *F. Lin*
Inventor Signature

Inventor Name: Kuan-Liang Wu

Residence Address: 7F, No. 23, Lane 294, Guangfu S. Road, Dan-an District
Taipei City 106, Taiwan, R.O.C.

Dated: ✓ 9/11/2008

✓ *Kuan-Liang Wu*
Inventor Signature

Docket No.: 2008-0326 / 24061.1095
Customer No.: 42717

Inventor Name: Che-Rong Laing

Residence Address: SF, No. 7, Land 120, Hulin Street, Sinyi District
Taipai City 110, Taiwan, R.O.C.

Dated: _____

Inventor Signature

Inventor Name: Fei-Gwo Tsai

Residence Address: 20F-5, No. 19, Lane 370, Gongyuan S. Road East District
Tainan City 704, Taiwan, R.O.C.

Dated: ✓ 9/11 /2008

✓ Fei-Gwo Tsai

Inventor Signature

ASSIGNMENT

WHEREAS, I,

(1) Che-Rong Liang of 5F, No. 7, Land 120, Hulin Street, Sinyi District
Taipei City 110, Taiwan, R.O.C.

have invented certain improvements in

HYBRID MULTI-LAYER MASK

for which I have executed an application for Letters Patent of the United States of America,

X filed on October 13, 2008 and assigned application no. 12/250,338 and;

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu, Taiwan 300-77, Republic of China. is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for One Dollar (\$1.00) and other good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, I have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and I hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND I HEREBY covenant that I have full right to convey the entire interest herein assigned, and that I have not executed, and will not execute, any agreement in conflict herewith.

AND I HEREBY further covenant and agree that I will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name: Che-Rong Liang

Residence Address: 5F, No. 7, Land 120, Hulin Street, Sinyi District
Taipei City 110, Taiwan, R.O.C.

Dated: ✓ Sep 11, 2009

✓ Che-Rong Liang
Inventor Signature